

Description

The IRFR5505TRPBF uses advanced trench technology

to provide excellent $R_{\text{DS}(\text{ON})},$ low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = -60V I_D =-15 A

 $R_{DS(ON)} < 82m\Omega @ V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply

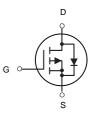
Package Marking and Ordering Information

| <u> </u> | 0 | | |
|---------------|-----------|-------------|----------|
| Product ID | Pack | Marking | Qty(PCS) |
| IRFR5505TRPBF | TO-252-2L | FR5505 XXXX | 2500 |

Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|---------------------------------------|---|--|-------|
| Vds | Drain-Source Voltage | -60 | V |
| Vgs | Gate-Source Voltage | ±20 | V |
| I₀@Tc=25°C | Continuous Drain Current, V _{GS} @ -10V ¹ | -15 | А |
| I _D @T _C =100°C | Continuous Drain Current, V _{GS} @ -10V ¹ | Is Drain Current, V_{GS} @ -10 V^1 -11 | |
| Ідм | Pulsed Drain Current ² | Pulsed Drain Current ² -36 | |
| EAS | Single Pulse Avalanche Energy ³ | 35.4 | mJ |
| las | Avalanche Current | ent -26.6 | |
| P₀@Tc=25°C | Total Power Dissipation ⁴ | Total Power Dissipation ⁴ 34.7 | |
| P _D @T _A =25°C | Total Power Dissipation ⁴ | 2 | |
| Тятд | Storage Temperature Range | erature Range -55 to 150 | |
| TJ | Operating Junction Temperature Range | -55 to 150 | °C |
| R _{0JA} | Thermal Resistance Junction-Ambient ¹ | 62 | °C/W |
| Rejc | Thermal Resistance Junction-Case ¹ | 3.6 °C/W | |





P-Channel MOSFET



IRFR5505TRPBF

P-Channel Enhancement Mode MOSFET

Electrical Characteristics (T_A=25°Cunless otherwise noted)

| Symbol | nbol Parameter Conditions | | Min. | Тур. | Max. | Unit |
|--------------------------------------|---|---|------|-------|------|--------------|
| BVDSS | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =-250uA | -60 | | | V |
| $\triangle B$ vdss / $\triangle T$ j | BV _{DSS} Temperature Coefficient | Reference to 25° C , I _D =-1mA | | -0.03 | | V/° C |
| | | V _{GS} =-10V , I _D =-12A | | 70 | 82 | |
| Rds(on) | Static Drain-Source On-Resistance | V _{GS} =-4.5V , I _D =-8A | | 85 | 105 | mΩ |
| VGS(th) | Gate Threshold Voltage | | -1.2 | 1.5 | -2.5 | V |
| $	riangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | V _{GS} =V _{DS} , I _D =-250uA | | 4.56 | | mV/°C |
| | | V _{DS} =-48V , V _{GS} =0V , TJ=25℃ | | | 1 | |
| loss | Drain-Source Leakage Current | rent V _{DS} =-48V , V _{GS} =0V , T _J =55°C | | | 5 | uA |
| lgss | Gate-Source Leakage Current | V _{GS} =±20V , V _{DS} =0V | | | ±100 | nA |
| gfs | Forward Transconductance | V _{DS} =-5V , I _D =-12A | | 15.4 | | S |
| Rg | Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | | 13.5 | | Ω |
| Qg | Total Gate Charge (-4.5V) | | | 9.86 | | |
| Qgs | Gate-Source Charge | V _{DS} =-48V , V _{GS} =-4.5V , I _D =-10A | | 3.08 | | nC |
| Q _{gd} | Gate-Drain Charge | - | | 2.95 | | |
| Td(on) | Turn-On Delay Time | | | 28.8 | | |
| Tr | Rise Time | V _{DD} =-15V , V _{GS} =-10V , | | 19.8 | | |
| Td(off) | Turn-Off Delay Time | - R _G =3.3□, I _D =-1A | | 60.8 | | ns |
| T _f | Fall Time | - | | 7.2 | | |
| Ciss | Input Capacitance | | | 1447 | | |
| Coss | Output Capacitance | V _{DS} =-15V , V _{GS} =0V , f=1MHz | | 97.3 | | pF |
| Crss | Reverse Transfer Capacitance | | | 70 | | |
| ls | Continuous Source Current ^{1,5} | | | | -18 | А |
| lsм | Pulsed Source Current ^{2,5} | $V_G=V_D=0V$, Force Current | | | -36 | A |
| Vsd | Diode Forward Voltage ² | V _{GS} =0V , I _S =-1A , T _J =25℃ | | | -1.2 | V |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1mH, I_{AS} =-26.6A

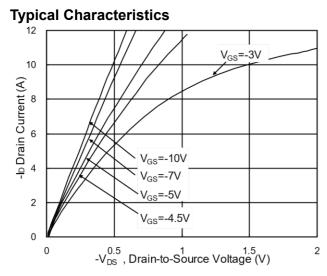
4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



IRFR5505TRPBF

P-Channel Enhancement Mode MOSFET





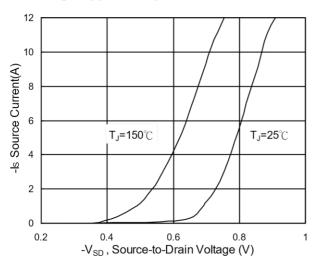
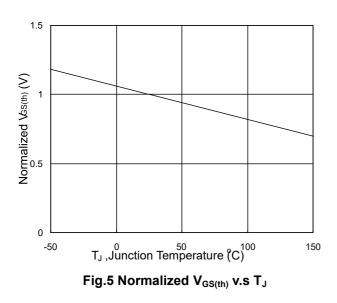


Fig.3 Forward Characteristics of Reverse



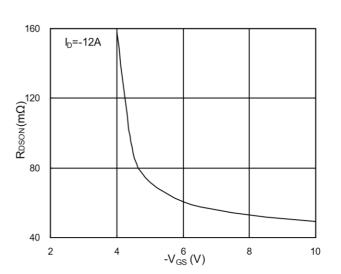


Fig.2 On-Resistance v.s Gate-Source

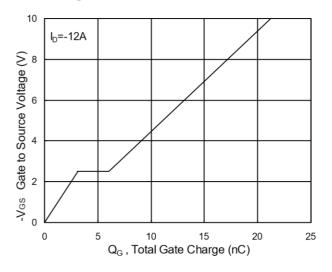
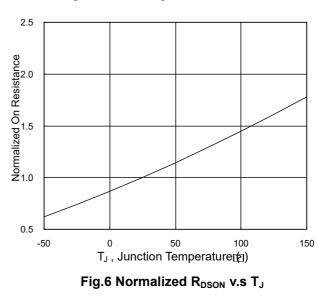


Fig.4 Gate-Charge Characteristics





IRFR5505TRPBF

P-Channel Enhancement Mode MOSFET

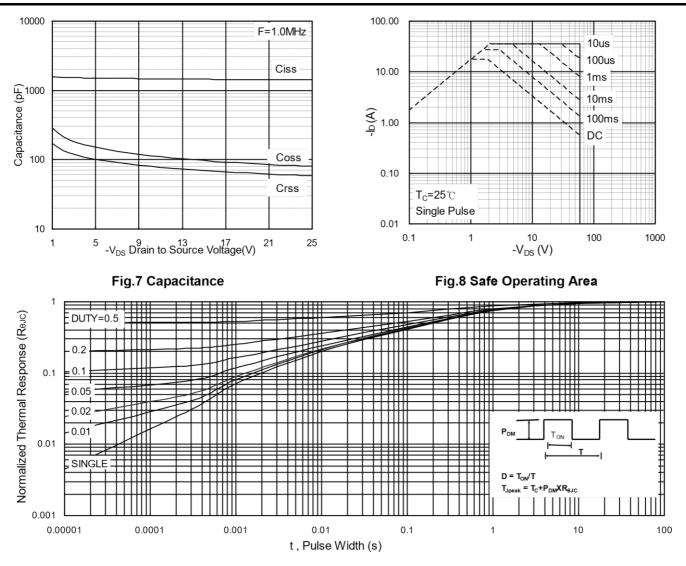


Fig.9 Normalized Maximum Transient Thermal Impedance

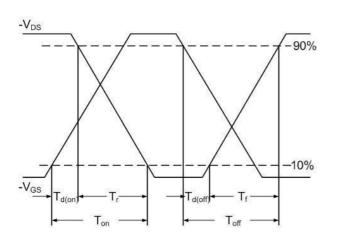
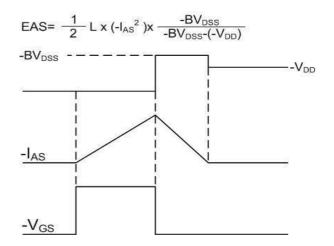


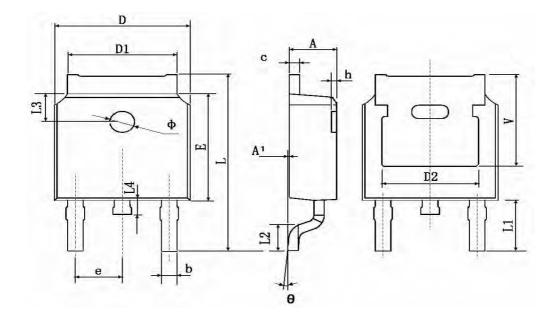
Fig.10 Switching Time Waveform







TO-252-2L Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|--------|----------------------|-------|--|
| | Min. | Max. | Min. | Max. | |
| A | 2.200 | 2.400 | 0.087 | 0.094 | |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 | |
| b | 0.660 | 0.860 | 0.026 | 0.034 | |
| с | 0.460 | 0.580 | 0.018 | 0.023 | |
| D | 6.500 | 6.700 | 0.256 | 0.264 | |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 | |
| D2 | 4.830 TYP. | | 0.190 TYP. | | |
| E | 6.000 | 6.200 | 0.236 | 0.244 | |
| e | 2.186 | 2.386 | 0.086 | 0.094 | |
| L | 9.800 | 10.400 | 0.386 | 0.409 | |
| L1 | 2.900 TYP. | | 0.114 TYP. | | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 | |
| L3 | 1.600 TYP. | | 0.063 TYP. | | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 | |
| Φ | 1.100 | 1.300 | 0.043 | 0.051 | |
| θ | 0° | 8° | 0° | 8° | |
| h | 0.000 | 0.300 | 0.000 | 0.012 | |
| V | 5.350 TYP. 0.211 TYP. | | TYP. | | |



Attention

Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.

• HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.

• Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

• HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could

give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

• In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

• No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.

Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production.
HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by HXY MOS manufacturer:

Other Similar products are found below :

IRFD120 JANTX2N5237 2SK2267(Q) BUK455-60A/B TK100A10N1,S4X(S MIC4420CM-TR VN1206L NDP4060 SI4482DY IRS2092STRPBF-EL IPS70R2K0CEAKMA1 TK31J60W5,S1VQ(O TK31J60W,S1VQ(O TK16J60W,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 DMC2700UDMQ-7 DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 IPS60R360PFD7SAKMA1 DMN2990UFB-7B SSM3K35CT,L3F IPLK60R1K0PFD7ATMA1 2N7002W-G MCAC30N06Y-TP IPWS65R035CFD7AXKSA1 MCQ7328-TP SSM3J143TU,LXHF DMN12M3UCA6-7 PJMF280N65E1_T0_00201 PJMF380N65E1_T0_00201 PJMF280N60E1_T0_00201 PJMF600N65E1_T0_00201 PJMF900N65E1_T0_00201